

**SEMICONDUCTOR ELEMENT PICKUP DEVICE**  
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**PURPOSE:** To minimize a damage to be applied to a semiconductor element by lifting the element adhering to an adhesive sheet by dividing by means of a needle, and providing a drive source for vertically moving the lifting needle separately from a drive source for a pickup tool when picking up it.

**CONSTITUTION:** A semiconductor element 2 adhering onto an adhesive sheet 1 by dividing is lifted upward by a lifting needle 4 driven by a first drive source 3 to facilitate the pickup of the element 2. Then, a second drive source 5 is operated in synchronization therewith, it is attracted by a pickup tool 6 and conveyed. The source 3 is controlled by a numerical controller 7. Thus, the element 2 is separately lifted and picked up by the drive sources, the moving distance and speed of the needle 4 are freely set, and the condition of stably picking it can be easily set.

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